JEDEC
STANDARD

Inspection Criteria for Microelectronic Packages and Covers

JESD9B

(Revision of JESD9A, April 1987)

MAY 2011

JEDEC SOLID STATE TECHNOLOGY ASSOCIATION

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Published by
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INSPECTION CRITERIA FOR MICROELECTRONIC PACKAGES AND COVERS

Contents

Page
Foreword **ii**
1 Scope **1**
2 Normative Reference **1**
3 Terms and Definitions **2**
4 General Requirements **10**
4.1 Quality System 10
4.2 Quality and Screening 10
4.3 Order of Precedence 10
4.4 Inspection Magnification 10
4.5 Controlling Dimension 10
5 Insulator Criteria (Metal Packages: Glass-to-metal and Ceramic-to-metal Seals) **11**
5.1 Insulator Bubbles 11
5.2 Insulator Cracks, Chip-outs, Crazing 13
5.3 Insulator Climb, Overflow, Splatter 17
5.4 Other Insulator Conditions 19
6 Braze Criteria (Metal Packages) **21**
6.1 Undercut Braze, Non-continuous Braze, Misalignment 21
6.2 Porous and Peeling Braze 22
6.3 Braze Run-out 23
6.4 Braze Climb 24
7 Leads (Metal and Ceramic Packages) **26**
7.1 Lead Nicks, Pits, Voids, Indentations, Scratches, Over-etching, Protrusions 26
7.2 Lead Surface Finish 29
7.3 Off-center, Bent, Angled, or Broken Leads 31
8 General Package Criteria (Metal Packages) **34**
8.1 Package Nicks, Pits, Voids, Indentations, Scratches, Protrusions, Chip-outs 34
8.2 Package Surface Finish 40
9 General Cover Criteria (Metal Covers) **42**
9.1 Cover Nicks, Pits, Voids, Indentations, Scratches, Protrusions, Chip-outs 42
9.2 Cover Surface Finish 45
10 General Package Criteria (Ceramic Packages: Non-metallized Areas) **46**
10.1 Ceramic Chip-outs, Cracks, Delamination, Separation, Voiding, Protrusions, Fins 46
11 Metallization Criteria (Ceramic Packages) **50**
11.1 General 50
11.2 Contact Pad Metallization 50
11.3 Seal Area Metallization 53
11.4 Bonding Area Metallization 57
11.5 Die Attach Area 61
11.6 Braze Pad Metallization 64
11.7 Castellation Metallization 66
12 Lead Attachment (Ceramic Packages) **67**
12.1 Lead to Braze Pad Attachment 67
12.2 Lead to Pad Misalignment 69
Annex A (informative) Index of Figures **70**
Annex B (informative) Differences between revisions **73**

Foreword

The purpose of this JEDEC standard is to verify the workmanship and requirements of microelectronic packages and covers (lids) intended for use in fabricating hybrid microelectronic circuits / microcircuits (hereafter referred to as “microcircuits”). It is applicable for use by the package manufacturer (i.e., package components), and the microcircuit manufacturer (i.e., from incoming inspection of package components through final inspection of the completed microcircuit).

This standard implements a complete re-write and significant technical changes and information from the previous edition.

This standard also encompasses and replaces JESD27, *Ceramic Package Specification for Microelectronic Packages*. It is meant to be used in conjunction, and to not contradict, with MIL-STD-883, Test Method 2009: External Visual. This standard provides the package manufacturer, microcircuit manufacturer, and microcircuit customer a complete set of microelectronic package workmanship inspection requirements.

INSPECTION CRITERIA FOR MICROELECTRONIC PACKAGES AND COVERS

(From JEDEC Board Ballot JCB-11-23, formulated under the cognizance of the JC-13.5 Committee on Hybrid Microcircuit Technology)

1 Scope

This standard establishes the inspection criteria for metal and ceramic hermetic packages, individual feed throughs, and covers (lids).

2 Normative Reference

The following normative documents contain provisions that, through reference in this text, constitute provisions of this standard. For dated references, subsequent amendments to, or revisions of, any of these publications do not apply. However, parties to agreements based on this standard are encouraged to investigate the possibility of applying the most recent editions of the normative documents indicated below. For undated references, the latest edition of the normative document referred to applies.

MIL-PRF-38534, *Hybrid Microcircuits, General Specification for*

MIL-PRF-38535, *Microcircuits, General Specification for*

MIL-STD-883, *Test Method Standard, Microcircuits*

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